



Timothy A. Teckman **Vice President of Engineering**

Mr. Teckman joined MathStar as Vice President of Engineering in April 2005. Mr. Teckman is responsible for all aspects of MathStar's Field Programmable Object Array (FPOA) product line, including product planning, product design, end-user tools and applications development. Mr. Teckman joined MathStar from Intel Corporation where he gained twenty years of broad engineering and management experience in strategic planning, new product development, product marketing, worldwide sales, and general management. Mr. Teckman's career has focused on identifying new technologies, creating new products based on those technologies leading to new businesses and market segments. He has a proven record of successfully leading technology-oriented, entrepreneurial product development organizations.

From 2003-2005, Mr. Teckman served as Director of Product Development for Intel's WiMAX Broadband Wireless Division, where he developed corporate strategic plans and product roadmaps, and led the development of the industry's first generation of WiMAX products. First silicon and software began shipping in 2005, establishing Intel as the industry leader in WiMAX broadband wireless products and standards. From 1999-2003, Mr. Teckman served Intel as General Manager of the Wireless Wide Area Network Operation, founding the operation through internal Intel Corporation venture funding, corporate acquisition and strategic partnerships. His team shipped their first products in 2002, against a multi-million dollar backlog. As Director of Marketing for the Pentium® III microprocessor from 1997-1999, Mr. Teckman led the marketing activities for the desktop Pentium® III processor product line, developing the PC platform roadmap, and microprocessor product positioning. From 1995-1997, he was the founder and General Manager of Intel's Corporate Client Business Unit, a new Intel business supplying business-oriented personal computer motherboards and systems to major personal computer OEMS. He developed the new business and product strategies and product line (including silicon, firmware, software and platform components) and achieved rapid revenue growth. As Engineering Manager for the Network Infrastructure Operations from 1992-1995, Mr. Teckman led product development teams in bringing to market branded networking products, including 10/100Mbps Ethernet silicon, PC cards and software, resulting in more than a 3X growth in Intel's Ethernet market segment share. From 1990-1992, Mr. Teckman served as Manager of Engineering Technology Development and was responsible for introducing VHDL development tools into several Intel divisions, and for creating the first dynamic bus modeling and simulation tools. Mr. Teckman began his Intel career as a Design Engineer, developing 80386-system products and PC memory products. He attended Miami University in Ohio as a Pre-Engineering and Physics major and received his BSEE from the University of Illinois Urbana.